DC Copper Plating for Thick Panel | 厚板高纵横比直流电镀铜技术

ELECTROPOSIT™ 1500 Acid Copper

The latest technology, ELECTROPOSIT™ 1500 Acid Copper, is developed by Dow Electronic Materials for thick panel plating which provides excellent throwing power than conventional products.

ELECTROPOSIT™ 1500电镀铜為陶氏化学电子材料所开发之最新一代应用于厚板之直流电镀技术。相较于过往产品，它能提供绝佳的通孔深镀能力。

Advantages 优点：

- High throwing power on high aspect ratio boards
  于高纵横比之厚板下具有高通孔深镀能力之表现
- Microvia plating capability
  可同时兼顾盲孔电镀
- Full Analysis System by CVS
  可使用CVS分析控管所有添加剂
- Excellent Thermal Reliability
  优异的热信赖度

Table 1: High throwing power on high aspect ratio boards
于高纵横比之厚板下，具有高通孔深镀能力之表现

Board thickness (mm)	2.36		3.25	
Hole Diameter (mm)	0.15	0.2	0.20	0.25
Aspect Ratio	15.7:1	11.8:1	16.25:1	13:1
C.D. (ASF)	10	10	6	6
TP% and Knee TP%	>90%	>95%	>95%	>90%

Table 2: Excellent Thermal Reliability
优异的热信赖度

Board thickness (mm)	3.25	3.25	2.36	2.36
Diameter (mm)	0.25	0.2	0.2	0.15
A/R	13:1	16.25:1	11.8:1	15.7:1
C.D. (ASF)	6	6	10	10
Reliability (Solder Float)	PASS	PASS	PASS	PASS

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